

Military 6226



SRAM

- Single 5.0 V $\pm$ 10% Power Supply
- Full Access Time — 35 ns Max.
- Equal Address and Chip Enable Access Time
- Three State Outputs
- Fully TTL Compatible
- Low Power Dissipation: 150/140/130 mA Maximum, Active AC
35 ns = 150 mA
45 ns = 140 mA
55 ns = 130 mA

1) JAN: N/A
2) SMD: Pending
3) 883C: 6226 - XX/BXAJC
X = CASE OUTLINE AS FOLLOWS:
PACKAGE: DIL: X
LCC: U
XX = Speed in ns (35, 45, 55)
The letter "M" appears after the
speed on LCC

The diagram illustrates the internal architecture of a 256Kb DRAM. It features a central **MEMORY ARRAY (512 ROWS 2048 COLUMNS)**. Address lines **A** (8 lines) are connected to a **ROW DECODER**, which selects one of the 512 rows in the array. Data lines **DQ₀** through **DQ₇** are connected to an **INPUT DATA CONTROL** block, which manages data flow between the array and the external data bus. The **INPUT DATA CONTROL** is also connected to a **COLUMN I/O** block and a **COLUMN DECODER**. The **COLUMN DECODER** selects one of the 2048 columns in the array. The **COLUMN I/O** block handles the data transfer between the array and the external data bus. Control signals **E**, **E_W**, and **G** are used to enable the row decoder, input data control, and column decoder, respectively. The diagram shows the complex interconnection of these components, including the use of inverters and AND/OR gates to manage the data and control signals.

**MOTOROLA**

T-46-23-14

BURN-IN CONDITIONS:

$V_{CC} = 5.0 \text{ V(min)}/6.0 \text{ V(max)}$, $R_1 = 39.2 \text{ k}\Omega \pm 20\%$, $C_1 = 0.1 \text{ }\mu\text{F} \pm 20\%$,
 $V_H = 3.0 \text{ V(min)}/5.0 \text{ V(max)}$, $V_L = -0.5 \text{ V(min)}/0.0 \text{ V(max)}$,

CP1: 100 kHz CP6: 3.125 kHz CP11: 97.66 Hz CP16: 3.052 Hz
 CP2: 50 kHz CP7: 1.563 kHz CP12: 48.83 Hz CP17: 1.526 Hz
 CP3: 25 kHz CP8: 0.781 kHz CP13: 24.41 Hz CP18: 0.763 Hz
 CP4: 12.5 kHz CP9: 0.391 kHz CP14: 12.21 Hz CP19: 0.382 Hz
 CP5: 6.25 kHz CP10: 0.195 kHz CP15: 6.104 Hz CP20: 0.191 Hz

PIN NAME and FUNCTIONS

$A_0 - A_{16}$	Address Inputs
$\overline{W}$	Write Enable
$\overline{E}$, E	Chip Enable
$\overline{G}$	Output Enable
$DQ_0 - DQ_7$	Data Input/Output
V_{CC}	+ 5.0 V Power Supply
V_{SS}	Ground
N.C.	No Connection

This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields; however, it is advised that normal precautions be taken to avoid application of any voltages higher than maximum rated voltages to this high-impedance circuit.

PIN ASSIGNMENTS

Function	DIL	LCC	Burn-In (Condition-D)
N.C.	1	1	N.C.
A_{16}	2	2	CP2
A_{14}	3	3	CP3
A_{12}	4	4	CP4
A_7	5	5	CP5
A_6	6	6	CP6
A_5	7	7	CP7
A_4	8	8	CP8
A_3	9	9	CP9
A_2	10	10	CP10
A_1	11	11	CP11
A_0	12	12	CP12
DQ_0	13	13	CP20 to R_1
DQ_1	14	14	CP20 to R_1
DQ_2	15	15	CP20 to R_1
V_{SS}	16	16	GND
DQ_3	17	17	CP20 to R_1
DQ_4	18	18	CP21 to R_1
DQ_5	19	19	CP21 to R_1
DQ_6	20	20	CP21 to R_1
DQ_7	21	21	CP21 to R_1
$\overline{E}$	22	22	GND
A_{10}	23	23	CP18
$\overline{G}$	24	24	CP19
A_{11}	25	25	CP17
A_9	26	26	CP16
A_8	27	27	CP15
A_{13}	28	28	CP14
$\overline{W}$	29	29	CP1
E	30	30	HIGH
A_{15}	31	31	CP13
V_{CC}	32	32	V_{CC} , C_1 to GND

T-46-23-14

TRUTH TABLE						
$\bar{E}$	$\bar{G}$	$\bar{W}$	Mode	V _{CC} Current	I/O Pin	Cycle
H	X	X	Not Selected	I _{SB1} , I _{SB2}	High Z	—
L	H	H	Read	I _{CCA}	High Z	—
L	L	H	Read	I _{CCA}	D _{OUT}	Read Cycle
L	X	L	Write	I _{CCA}	D _{IN}	Write Cycle

X = Don't Care

ABSOLUTE MAXIMUM RATINGS (See Note)			
Rating	Symbol	Value	Unit
Power Supply Voltage	V _{CC}	- 0.5 to + 7.0	V
Voltage Relative to V _{SS} for Any Pin Except V _{CC}	V _{IN} , V _{OUT}	- 0.5 to V _{CC} + 5.0	V
Output Current	I _{OUT}	±20	mA
Power Dissipation	P _D	1.0	W
Temperature Under Bias (T _A = 25°C)	T _{bias}	- 55 to +125	°C
Storage Temperature Range	T _{stg}	- 65 to +150	°C
Operating Temperature Range	T _A	- 55 to +125	°C

NOTE: Permanent device damage may occur if ABSOLUTE MAXIMUM RATINGS are exceeded. Functional operation should be restricted to RECOMMENDED OPERATING CONDITIONS. Exposure to higher than recommended voltages for extended periods of time could affect device reliability.

DC OPERATING CONDITIONS AND CHARACTERISTICS

(V_{CC} = 5.0 V ±10%, T_A = - 55°C to +125°C, Unless Otherwise Noted)

RECOMMENDED OPERATING CONDITIONS					
Parameter	Symbol	Min	Typ	Max	Unit
Supply Voltage (Operating Voltage Range)	V _{CC}	4.5	5.0	5.5	V
Input High Voltage	V _{IH}	2.2	—	V _{CC} + 0.3	V
Input Low Voltage	V _{IL}	- 0.5 *	—	0.8	V

* V_{IL} (min) = - 0.5 Vdc; V_{IL} (min) = - 3.0 Vdc (pulse width ≤ 20 ns)

T-46-23-14

DC CHARACTERISTICS					
Parameter	Symbol	Min	Typ	Max	Unit
Input Leakage Current (All Inputs, $V_{in} = 0$ to V_{CC})	$I_{kg(I)}$	—	—	± 5.0	μA
Output Leakage Current ($\bar{E} = V_{IH}$, $V_{OUT} = 0$ to V_{CC})	$I_{kg(O)}$	—	—	± 5.0	μA
AC Supply Current ($I_{OUT} = 0$ mA)	6226-35: $t_{AVAV} = 35$ ns	—	—	150	mA
	6226-45: $t_{AVAV} = 45$ ns	—	—	140	mA
	6226-55: $t_{AVAV} = 55$ ns	—	—	130	mA
TTL Standby Current ($\bar{E} = V_{IH}$, No Restrictions on Other Inputs)	I_{SB1}	—	30	40	mA
CMOS Standby Current ($\bar{E} \geq V_{CC} - 2.0$ V, No Restrictions on Other Inputs)	I_{SB2}	—	20	30	mA
Output Low Voltage ($I_{OL} = 8.0$ mA)	V_{OL}	—	—	0.4	V
Output High Voltage ($I_{OH} = -4.0$ mA)	V_{OH}	2.4	—	—	V

CAPACITANCE ($f = 1.0$ MHz, $dV = 3.0$ V, $T_A = 25^\circ C$, Periodically Sampled Rather Than 100% Tested)					
Characteristic	Symbol	Typ	Max	Unit	
Input Capacitance All Inputs Except $\bar{E}$, E and DQ	C_{in}	4.0	6.0	pF	
		5.0	7.0	pF	
I/O Capacitance DQ	$C_{I/O}$	5.0	7.0	pF	

T-46-23-14

AC OPERATING CONDITIONS AND CHARACTERISTICS

(VCC = 5.0 V $\pm$ 10%, T_A = -55°C to +125°C, Unless Otherwise Noted)

Input Timing Measurement Reference Level	1.5 V
Input Pulse levels	0 to 3.0 V
Input Rise/Falls Time	≥ 5.0 ns
Output Timing Measurement Reference Level	1.5 V
Output Load	See Figure 1A

READ CYCLE (See Note 1)										
Parameter	Symbol Standard	Symbol Alternate	6226-35		6226-45		6226-55		Unit	Notes
			Min	Max	Min	Max	Min	Max		
Read Cycle Time	t _{AVAV}	t _{RC}	35	—	45	—	55	—	ns	2
Address Access Time	t _{AVQV}	t _{AA}	—	35	—	45	—	55	ns	—
Enable Access Time	t _{ELQV}	t _{ACS}	—	35	—	45	—	55	ns	—
Output Enable Access Time	t _{GLQV}	t _{OE}	—	15	—	15	—	20	ns	—
Output Hold from Address Change	t _{AXQX}	t _{OH}	5.0	—	5.0	—	5.0	—	ns	—
Enable Low to Output Active	t _{ELQX}	t _{LZ}	5.0	—	5.0	—	5.0	—	ns	3, 4, 5
Enable High to Output High-Z	t _{EHQZ}	t _{HZ}	—	15	—	15	—	20	ns	3, 4, 5
Output Enable to Output Active	t _{GLQX}	t _{LZ}	0	—	0	—	0	—	ns	3, 4, 5
Output Enable to Output High-Z	t _{GLQZ}	t _{HZ}	0	15	0	15	0	20	ns	3, 4, 5
Power Up Time	t _{ELICCH}	t _{PU}	0	—	0	—	0	—	ns	5
Power Down Time	t _{EHICCL}	t _{PD}	—	35	—	45	—	55	ns	5

NOTES:

1. $\bar{W}$ is high for read cycle.
2. All read cycle timing is referenced from the last valid address to the first transitioning address.
3. A any given voltage and temperature, t_{EHQZ} max is less than t_{ELQX} min, and t_{GHQX} max is less than t_{GHQX} min, both for a given device and from device to device.
4. Transition is measured ± 500 mV from steady-state voltage with load of Figure 1B.
5. These parameters are periodically sampled and not 100% tested.
6. Device is continuously selected ($\bar{E} = V_{IL}$, $E = V_{IH}$, $\bar{G} = V_{IL}$).
7. Address valid prior to coincident with $\bar{E}$ going low/ E going high.

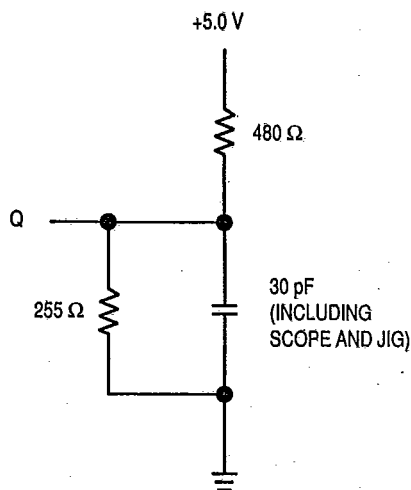
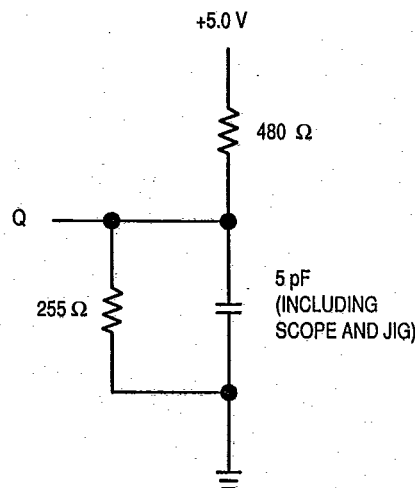
T-46-23-14

WRITE CYCLE 1 ($\bar{W}$ Controlled, See Note 1)

Parameter	Symbol Standard	Symbol Alternate	6226-35		6226-45		6226-55		Unit	Notes
			Min	Max	Min	Max	Min	Max		
Write Cycle Time	t_{AVAV}	t_{WC}	35	—	45	—	55	—	ns	2
Address Setup Time	t_{AVWL}	t_{AS}	0	—	0	—	0	—	ns	—
Address Valid to End of Write	t_{AVWH}	t_{AW}	20	—	20	—	30	—	ns	—
Write Pulse Width	t_{WLWH}	t_{WP}	20	—	20	—	30	—	ns	—
Data Valid to End of Write	t_{DVWH}	t_{DW}	15	—	15	—	20	—	ns	—
Data Hold Time	t_{WHDX}	t_{DH}	0	—	0	—	0	—	ns	—
Write Low to Data High-Z	t_{WLQZ}	t_{WZ}	0	15	0	15	0	20	ns	4, 5, 6
Write High to Output Active	t_{WHQX}	t_{OW}	0	—	0	—	0	—	ns	4, 5, 6
Write Recovery Time	t_{WHAX}	t_{WR}	0	—	0	—	0	—	ns	—

NOTES:

1. A write occurs during the overlap of $\bar{E}$ low/E high and $\bar{W}$ low.
2. All write cycle timing is referenced from the last valid address to the first transitioning address.
3. Transition is measured ± 500 mV from steady-state voltage with load of Figure 1B.
4. Parameters is sampled and not 100% tested.
5. A any given voltage and temperature, t_{WLQZ} max is less than t_{WHQX} min both for a given device and from device to device.

AC TEST LOADS

Figure 1A.

Figure 1B.

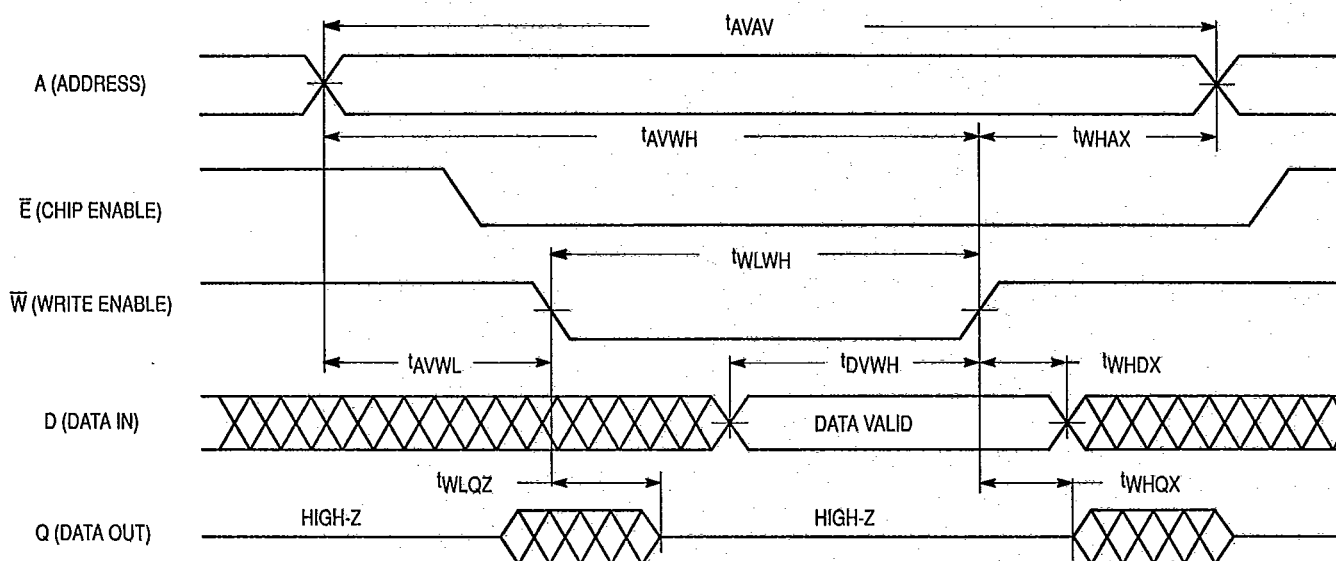
T-46-23-14

WRITE CYCLE 2 ($\bar{E}$ Controlled, See Note 1)

Parameter	Symbol Standard	Symbol Alternate	6226-35		6226-45		6226-55		Unit	Notes
			Min	Max	Min	Max	Min	Max		
Write Cycle Time	t_{AVAV}	t_{WC}	35		45		55		ns	2
Address Setup Time	t_{AVEL}	t_{AS}	0		0		0		ns	
Address Valid to End of Write	t_{AVEH}	t_{AW}	20		25		30		ns	
Enable to End of Write	t_{ELEH}	t_{CW}	20		25		30		ns	3, 4
Write Pulse Width	t_{WLEH}	t_{WP}	20		25		30		ns	
Data Valid to End of Write	t_{DVEH}	t_{DW}	15		15		20		ns	
Data Hold Time	t_{EHDX}	t_{DH}	0		0		0		ns	
Write Recovery Time	t_{EHAX}	t_{WR}	0		0		0		ns	

NOTES:

1. A write occurs during the overlap of $\bar{E}$ low/ E high and $\bar{W}$ low.
2. All write cycle timing is referenced from the last valid address to the first transitioning address.
3. If $\bar{E}$ goes low coincident with or after $\bar{W}$ goes low, the output will remain in a high impedance condition.
4. If $\bar{E}$ goes high coincident with or after $\bar{W}$ goes high, the output will remain in a high impedance condition.

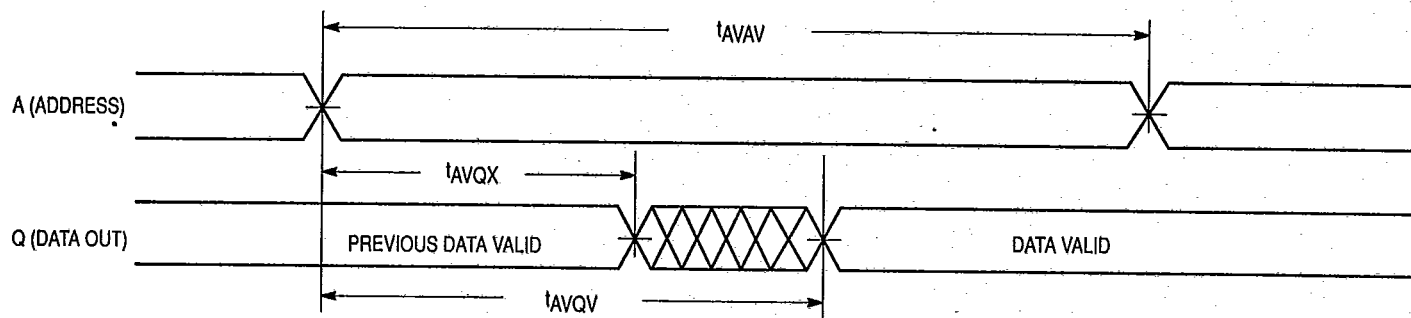
WRITE CYCLE 1 ($\bar{W}$ Controlled)

TIMING LIMITS

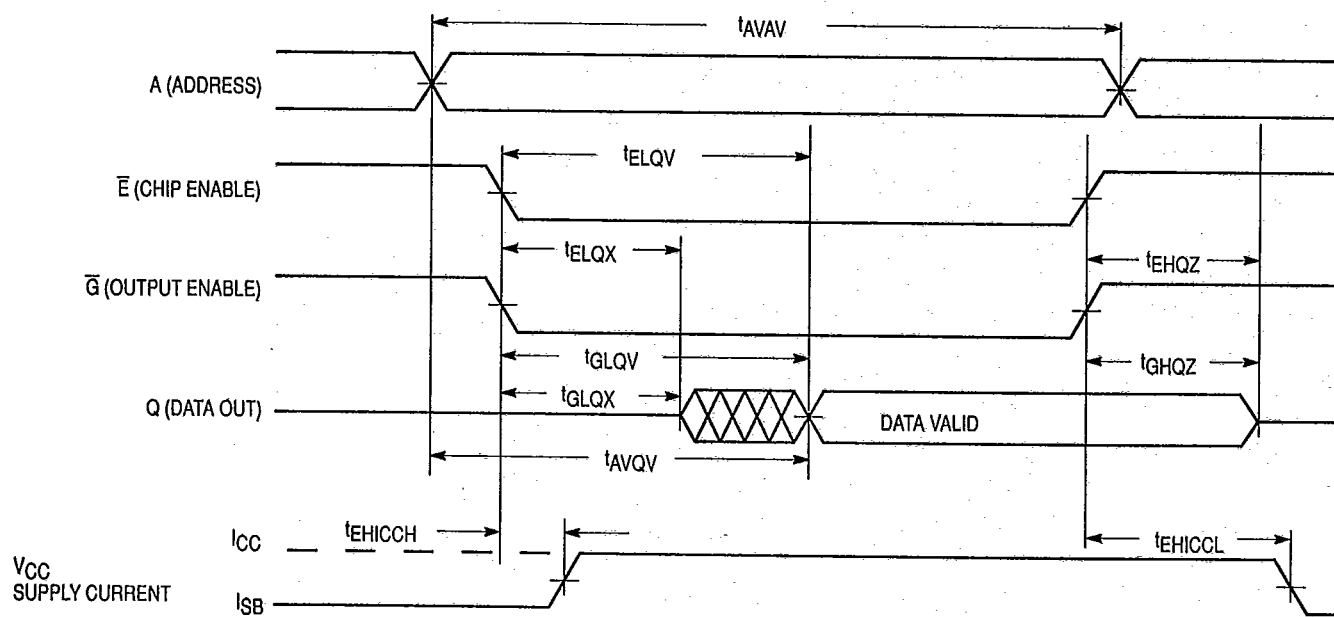
The table of timing values shows either a minimum or a maximum limit for each parameter. Input requirements are specified from the external system point of view. Thus, address setup time is shown as a minimum since the system must supply at least that much time (even though most devices do not require it). On the other hand, responses from the memory are specified from the device point of view. Thus, the access time is shown as a maximum since the device never provides data later than that time.

READ CYCLE 1 (See Note 6 above)

T-46-23-14



READ CYCLE 2 (See Note 7 above)



T-46-23-14

WRITE CYCLE 2 ($\bar{E}$ Controlled)

